

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takashi YOKOKAWA	03/24/2010
Makiko YAMAMOTO	03/25/2010
Satoshi OKADA	03/25/2010
Lui SAKAI	03/26/2010
Ryoji IKEGAYA	03/25/2010

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12743487

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	359790US8PCT
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NAME OF SUBMITTER:	Teresa Pena
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Total Attachments: 2
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**PATENT
 REEL: 024451 FRAME: 0302**

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

~~Description~~

DATA PROCESSING APPARATUS, DATA PROCESSING METHOD AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.: PCT/JP2008/071399 . International Filing Date: November 26, 2008

This assignment executed on the dates indicated below.

TAKASHI YOKOKAWA

Name of first or sole inventor

KANAGAWA JAPAN

Residence of First or sole inventor

Takashi Yokokawa
Signature of first or sole inventor

Execution date of U.S. Patent Application

March 24, 2010
Date of this assignment

MAKIKO YAMAMOTO

Name of second inventor

TOKYO JAPAN

Residence of second inventor

Makiko Yamamoto
Signature of second inventor

Execution date of U.S. Patent Application

March 25, 2010
Date of this assignment

SATOSHI OKADA

Name of third inventor

TOKYO JAPAN

Residence of third inventor

Satoshi Okada
Signature of third inventor

Execution date of U.S. Patent Application

March 25, 2010
Date of this assignment

ADDITIONAL INVENTOR(S)

LUI SAKAI
Name of fourth inventor
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Residence of fourth inventor
Lui Sakai
Signature of fourth inventor

Execution date of U.S. Patent Application
March 26, 2010
Date of this assignment

RYOJI IKEGAYA
Name of fifth inventor
KANAGAWA JAPAN
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Ryoji Ikegaya
Signature of fifth inventor

Execution date of U.S. Patent Application
March 25, 2010
Date of this assignment

Name of sixth inventor
Residence of sixth inventor
Signature of sixth inventor

Execution date of U.S. Patent Application
Date of this assignment

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Execution date of U.S. Patent Application
Date of this assignment